

Low-Cost RFID IC Packaging and Assembly Workshop

A private workshop hosted by Fraunhofer-IZM and TechSearch International, Inc.

November 14, 2005
Hansastraße 27c (Fraunhofer Haus)
Munich, Germany

Agenda

- 8:30 - 9:00 Registration and coffee
- 9:00 - 9:30 **Keynote and Introduction:**
Dr. Karlheinz Bock, Deputy Director, Munich Branch Fraunhofer-IZM
- 9:30 - 10:00 **Addressing the RFID Market Needs**
Guenther Aflenzer, Manager Packaging and Systems Integration Group, Philips Semiconductors
- 10:00 - 10:30 **RFID Tag Activity at Infineon**
Werner Koele, Technical Marketing, Memories and RFID, Infineon Technology
- 10:30 - 11:00 **Fluidic Self Assembly**
Glenn Gengel, Vice President of Manufacturing, Alien Technology Corp.
- 11:00 - 11:30 **SCP Technology: A Revolutionary Process Enabling the Low Cost High Quality Manufacturing of RFID Tags**
Holger Ulland, Head of Product Management RFID Solutions, Arccure Technologies
- 11:30 - 12:00 **RFID Chip and Tag Assembly Challenges**
Dr. Frank Kriebel, Vice President of Research & Development, KSW Microtec
- 12:00 - 1:00 Lunch
- 1:00 - 1:30 **Challenges of Low Cost Chip Assembly for RFID Inlay Production**
Dr. Hugo Pristauz, Director Advanced Technology & RFID Business Dev., Datacon Technology
- 1:30 - 2:00 **Technology Update: Different Options for High Volume Smart Label Production**
Thomas Betz, Director of Business Development, Mühlbauer AG
- 2:00 - 2:30 **The Challenge of Manufacturing Smart Labels**
Martin R. Bohn, Division Manager RFID, Bielomatik
- 2:30 - 3:00 **ACPINCP Solutions for High Speed Assembly of RFID Chips**
Stefan Mieslinger, Project Manager Smart Labels, Delo Industrial Adhesives
- 3:00 - 3:15 Break
- 3:15 - 3:45 **Low Cost Bumping for RFID Chips**
Dr. Elke Zakel, CEO, Pac Tech GmbH
- 3:45 - 4:15 **RFID Activities in Asia**
Tetsuya Onishi, Managing Director, Grand Joint Technology Ltd. (Hong Kong)
- 4:15 - 4:45 **Significant steps towards printed low-cost RFID**
Wolfgang Mildner, Managing Director, PolyIC
- 4:45 - 5:45 Panel Discussion: Key Challenges to Low Cost RFID Inlay and Tag Assembly
Moderator - Dr. Frank J. Bachner, Senior Analyst, TechSearch International Inc.
- 5:45 RECEPTION




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